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FLIP CHIP ON GLASS IMAGE SENSOR PACKAGE

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ABSTRACT

10 An image sensor package includes an image sensor
having an active area and bond pads on a front surface
of the image sensor. A window is mounted to the image
sensor by flip chip bumps formed between the bond pads
of the image sensor and interior traces on an interior
surface of the window. The window has an area less
than an area of the front surface of the image sensor.
A bead is formed between the window and the front
15 surface of the image sensor thus forming a sealed
cavity in which the active area is located. The bead
has sides coplanar with sides of the image sensor such
that the image sensor package is chip size.